EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	1	"20030032263"	US-PGPUB; USPAT	OR	ON	2007/05/03 09:17
S4	1357	438/462	US-PGPUB; USPAT	OR	ON	2007/05/03 09:46
S5	508	S4 and @py<"2003"	US-PGPUB; USPAT	OR	ON	2007/05/03 09:18
S6	1370	S5 and probe card or probe pad	US-PGPUB; USPAT	ADJ	ON	2007/05/03 09:19
S7	11	S5 and (probe card or probe pad)	US-PGPUB; USPAT	ADJ	ON	2007/05/03 09:20
S10	209	438/462,110,18,678.ccls. and 257/48.ccls.	US-PGPUB; USPAT	OR	ON	2007/05/03 09:24
S11	9	S5 and S10	US-PGPUB; USPAT	OR	ON	2007/05/03 09:26
S12	982606	integrated circuit same pads same bumps same (probe adj card or probe adj pad)	US-PGPUB; USPAT	OR	ON	2007/05/03 09:27
S13	69	integrated circuit same pads same bumps same (probe adj card or probe adj pad)	US-PGPUB; USPAT	ADJ	ON	2007/05/03 09:45
S14	32	S13 and @py<"2004"	US-PGPUB; USPAT	OR	ON	2007/05/03 09:44
S17	1	S4 and S3	US-PGPUB; USPAT	OR	ON	2007/05/03 09:46
S18	6	("2003/0032263").URPN.	USPAT	OR	ON	2007/05/03 09:51
S19	3155	bent wires	US-PGPUB; USPAT	ADJ	ON	2007/05/03 09:52
S20	2458	S19 and @py<"2004"	US-PGPUB; USPAT	OR	ON	2007/05/03 09:52
S21	63	S20 and integrated adj circuit	US-PGPUB; USPAT	OR	ON	2007/05/03 09:56
S24	642921	semiconductor wafer same integrated adj circuit and @py<"2004"	US-PGPUB; USPAT	OR	ON	2007/05/03 09:57
S25	10213	semiconductor wafer same integrated adj circuit and @py<"2004"	US-PGPUB; USPAT	ADJ	ON	2007/05/03 10:13
S26	10	S13 and S25	US-PGPUB; USPAT	OR	ON	2007/05/03 09:58
S27	2	("5430816" | "5945834").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 10:11

EAST Search History

S28	9	("4038599" | "4520314" | "4563640" | "4757255" | "4787752" | "4799009" | "4961052" | "4983907" | "5012187").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 10:11
S29	125	semiconductor wafer same integrated adj circuit same burn-in and @py<"2004"	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:39
S30	35	wafer level burn-in same integrated circuit same semiconductor wafer	US-PGPUB; USPAT	ADJ	ON	2007/05/03 10:53
S31	1	S13 and S30	US-PGPUB; USPAT	OR	ON	2007/05/03 10:56
S32	2785	438/613	US-PGPUB; USPAT	OR	ON	2007/05/03 10:56
S33	1440	S32 and @py<"2004"	US-PGPUB; USPAT	OR	ON	2007/05/03 10:57
S34	107	S33 and burn-in	US-PGPUB; USPAT	OR	ON	2007/05/03 10:57
S40	5	S33 and ULSI devices	US-PGPUB; USPAT	ADJ	ON	2007/05/03 11:13
S41	8	("5422435" | "5608262" | "5811351" | "5952725" | "5994166" | "6114187" | "6228681" | "6365499").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 11:14
S42	228	LSI same burn-in	US-PGPUB; USPAT	OR	ON	2007/05/03 11:15
S43	13	S25 and S42	US-PGPUB; USPAT	OR	ON	2007/05/03 11:15
S44	14	("3405361" | "4906920" | "4980637" | "5012187" | "5070297" | "5140405" | "5219765" | "5225037" | "5440241" | "5461326" | "5500604" | "5532610" | "5701666").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 12:21
S45	416102	angular wire same bump	US-PGPUB; USPAT	OR	ON	2007/05/03 12:22
S47	5087	(angular or bent or vent or comb-like or whorl-like) wire same bumps or probe (card or pad)	US-PGPUB; USPAT	ADJ	ON	2007/05/03 13:00
S49	2659	S47 and @py<"2004"	US-PGPUB; USPAT	OR	ON	2007/05/03 12:26
S50	1097	S49 and semiconductor same integrated circuit	US-PGPUB; USPAT	ADJ	ON	2007/05/03 13:01
S52	2	S51 and reduced same chip adj area	US-PGPUB; USPAT	OR	ON	2007/05/03 12:28

EAST Search History

S53	11	("3961254" | "4336495" | "4339710" | "4357703" | "4398146" | "4519076" | "4733168" | "4743841" | "4751679" | "4970454" | "5107208").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 12:33
S54	66	("4286173" | "4336495" | "4339710" | "4398146" | "4450402" | "4550289" | "4612499" | "4698588" | "4706157" | "4733168" | "4743841" | "4764924").PN. OR ("4970454").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 12:34
S55	4	("4703483" | "4910735" | "4945536" | "4970724").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 12:34
S56	341	S50 and burn-in	US-PGPUB; USPAT	OR	ON	2007/05/03 12:37
S57	277	S49 and surface adj area	US-PGPUB; USPAT	OR	ON	2007/05/03 13:02
S58	69	S49 and surface adj area same reduc$3	US-PGPUB; USPAT	OR	ON	2007/05/03 14:51
S60	486	semiconductor wiring	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:00
S61	48	semiconductor wiring same integrated circuits	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:07
S62	115	wring patterns	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:07
S63	20890	wiring patterns	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:08
S64	123	wiring patterns and 438/612.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:13
S66	1	wiring same probe card same bumps same pad and 438/612.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:15
S67	4579	257/737	US-PGPUB; USPAT	OR	ON	2007/05/03 15:15
S68	284137	probe card same bumps same pad same wire and 257/737.ccls.	US-PGPUB; USPAT	OR	ON	2007/05/03 15:16
S69	3	probe card same bumps same pad same wire and 257/737.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/05/03 15:19
S74	4	semiconductor wafer same integrated circuit same probe card same bumps same pad same wire	US-PGPUB; USPAT	WITH	ON	2007/05/03 15:23
S75	113	probe card same bumps same pad same wire	US-PGPUB; USPAT	WITH	ON	2007/05/03 15:23
S76	4950	wir$4 same contact same bump	US-PGPUB; USPAT	OR	ON	2007/05/03 15:39

S77	59	two adj wir$4 same contact same bump	US-PGPUB; USPAT	OR	ON	2007/05/03 15:46
S78	6	two adj wir$4 same contact near bump	US-PGPUB; USPAT	OR	ON	2007/05/03 15:47
S79	34821	two adj wir$4 nearcontact near bump	US-PGPUB; USPAT	OR	ON	2007/05/03 15:47
S81	1	two adj wir$4 with contact near bump	US-PGPUB; USPAT	OR	ON	2007/05/03 15:48
S82	166	wirings with contact near bump	US-PGPUB; USPAT	OR	ON	2007/05/03 15:48
S83	6	wirings with contact near bump	US-PGPUB; USPAT	OR	OFF	2007/05/03 15:52
S84	8	wirings with contact near bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/05/03 16:04
S89	2	two adj wir$4 adj contacts with bumps	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/03 16:07
S90	1	two adj wir$4 adj contacts with one adj bumps	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/03 16:07
S91	1	two adj (wir$4 or metal) adj contacts with one adj bumps	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/03 16:08
S92	1	integrated adj circuit same two adj (wir$4 or metal) adj contacts with one adj bumps	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/03 16:09

S93	1	integrated adj circuit same two adj (wir$4 or metal) adj contacts with one adj bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/03 16:09
S95	2	separated same wires same one adj bump	US-PGPUB; USPAT	OR	ON	2007/05/03 16:11
S96	121	wires same one adj bump	US-PGPUB; USPAT	OR	ON	2007/05/03 16:12
S98	4	two adj wires same one adj bump	US-PGPUB; USPAT	OR	ON	2007/05/03 16:12
S99	6	("20030047807" | "20040065880" | "6126059" | "6188044" | "6196002" | "6570250").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 16:22
S100	4	("5477160" | "6133744" | "6466038" | "6635970").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/03 16:25
S105	6	"6911834"	US-PGPUB; USPAT	OR	ON	2007/05/07 08:12
S106	2	("5982187" | "6404213").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/07 08:01
S108	22	multiple contacts with bump	US-PGPUB; USPAT	ADJ	ON	2007/05/07 08:16
S110	1	multiple wires with bump	US-PGPUB; USPAT	ADJ	OFF	2007/05/07 08:18
S111	6	two wires with bump	US-PGPUB; USPAT	ADJ	OFF	2007/05/07 08:25
S114	2	bump pad same two wires with bump	US-PGPUB; USPAT	ADJ	OFF	2007/05/07 08:28
S115	2	bump pad same two wires with bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/05/07 08:29
S116	1266	G01R31/02	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/05/07 08:38

S12 0	19	multiple contacts with solder (ball or bump)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/05/07 10:22
S12 2	6	multiple wires with solder (ball or bump)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/05/07 10:26
S12 3	6	two wires with solder (ball or bump)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/05/07 10:27
S12 4	35	("3795037" | "4636018" | "4667129" | "4793814" | "4998885" | "5061192" | "5098305" | "5355283" | "5531022" | "5764486" | "5772451" | "5917707" | "6078500").PN. OR ("6286208"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/07 11:12
S12 5	6	("5098305" | "5127837" | "5386341" | "5475317" | "5531022" | "5611696").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/07 10:44
S12 6	146	("5098305" | "5127837" | "5386341" | "5475317" | "5531022" | "5611696").PN. OR ("5772451"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/07 10:45
S13 2	5	wiring with separable portions	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:15
S13 3	1	wiring with separable portions and 257/737.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:19
S13 4	28	wiring with separa$ with pads with bump!	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:21
S13 8	687	wiring with separa$ with pads	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:22
S13 9	4991	S138 and two wires with bump!	US-PGPUB; USPAT	OR	ON	2007/05/07 15:34
S14 0	2	S138 and two wires with bump!	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:25
S14 2	2479	257/734	US-PGPUB; USPAT	OR	ON	2007/05/07 15:34

S143	1247	S142 and @py<"2004"	US-PGPUB; USPAT	OR	ON	2007/05/07 15:34
S144	75	S143 and S139	US-PGPUB; USPAT	OR	ON	2007/05/07 15:41
S145	0	S143 and two wires with bump!	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:41
S147	149	S143 and wires with bump	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:46
S148	2916	438/612	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:46
S149	2916	438/612 and py<"2004"	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:54
S150	77892	bumps or balls with separable wires with pads	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:55
S155	5918	(bumps or balls) with wires with pads	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:56
S157	1475054	multiple wires with bump and S155	US-PGPUB; USPAT	OR	ON	2007/05/07 15:57
S158	2	multiple wires with bump and S155	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:59
S159	1854	wires with bump! and S155	US-PGPUB; USPAT	ADJ	ON	2007/05/07 15:59
S160	857	wires with bump! and S155 and @py<"2004"	US-PGPUB; USPAT	ADJ	ON	2007/05/07 16:04
S164	1	Sogawa-yasuyo.in.	US-PGPUB; USPAT	OR	ON	2007/05/08 08:14
S165	8	nishikawa-kazuhiko.in.	US-PGPUB; USPAT	OR	ON	2007/05/08 08:12
S167	6	hirofuji-masanori.in.	US-PGPUB; USPAT	OR	ON	2007/05/08 08:10
S168	18	hirofuji-masanori.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/08 08:10
S169	56	nishikawa-kazuhiko.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/08 08:12

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S17 0	2	Sogawa-yasuyo.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/08 08:15
S17 1	152126	H01R 43/02	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/08 08:28
S17 2	32130	BGA or ball adj grid adj array	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/08 08:28
S17 3	32130	BGA or (ball adj grid adj array)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/08 08:28
S17 4	2	S173 and (solder adj balls or bumps)same two adj wires with bump	US-PGPUB; USPAT	OR	ON	2007/05/08 08:40
S17 5	4	("5326428" | "5374893" | "5604445" | "5634267").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/08 08:32
S17 6	20	("3596228" | "3663184" | "3832632" | "3839727" | "4042954" | "4237607" | "4273859" | "4293637" | "4661375" | "4836435" | "4878611" | "4950623" | "4975079" | "4975765" | "5006792" | "5007163" | "5065227" | "5073117" | "5088190" | "5108027").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/08 08:37
S17 7	2	S173 and two adj wires with bump	US-PGPUB; USPAT	OR	ON	2007/05/08 08:41
S17 9	4	two adj wires with one adj bump	US-PGPUB; USPAT	OR	ON	2007/05/08 09:13
S18 0	327	bumps with probe adj card	US-PGPUB; USPAT	OR	ON	2007/05/08 09:16

S18 1	4225838	two wires with bump with probe adj card	US-PGPUB; USPAT	OR	ON	2007/05/08 09:16
S18 3	18	two adj wires with bump	US-PGPUB; USPAT	OR	ON	2007/05/08 09:16
S18 7	327	probe card with bumps	US-PGPUB; USPAT	ADJ	ON	2007/05/08 11:11
S18 8	1	"20030116346"	US-PGPUB; USPAT	OR	ON	2007/05/08 11:17
S18 9	151	"5006792"	US-PGPUB; USPAT	OR	ON	2007/05/08 11:19
S19 0	168	"5073117"	US-PGPUB; USPAT	OR	ON	2007/05/08 13:30
S19 1	6	"026052"	US-PGPUB; USPAT	OR	ON	2007/05/08 13:33
S19 2	119	"5225037"	US-PGPUB; USPAT	OR	ON	2007/05/08 14:01
S19 4	66	MEMS same probe card	US-PGPUB; USPAT	ADJ	ON	2007/05/08 14:02
S19 5	1	"20030032263"	US-PGPUB; USPAT	OR	ON	2007/05/09 12:04
S19 6	6	"737943"	US-PGPUB; USPAT	OR	ON	2007/05/09 12:05
S19 7	6	"737943"	US-PGPUB; USPAT	OR	ON	2007/05/09 12:05
S19 8	10	"737943"	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2007/05/09 14:50
S19 9	4	"737943"	DERWENT	OR	ON	2007/05/09 14:51
S20 2	93	"4998885"	US-PGPUB; USPAT	OR	ON	2007/05/09 16:00
S20 3	126	"5371654"	US-PGPUB; USPAT	OR	ON	2007/05/09 16:24

S20 4	39	("2961746" | "3430338" | "3541222" | "3557446" | "3795037" | "3862790" | "3889363" | "3954317" | "4003621" | "4008300" | "4295700" | "4329780" | "4355199" | "4402562" | "4408814" | "4509099" | "4520562" | "4548451" | "4555523" | "4575166" | "4577918" | "4778950" | "4793814" | "4820170" | "4820376" | "4832609" | "4991290" | "4998885" | "5037312" | "5049084" | "5099309" | "5371654" | "5413489" | "5518410" | "5611696").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/09 16:14
S20 5	9	TEST CARD WITH BUMPS	US-PGPUB; USPAT	ADJ	ON	2007/05/09 16:24
S20 6	6	("3634807" | "3746973" | "4760335" | "4937203" | "5007163" | "5053698").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/09 16:36
S20 7	30	("3634807" | "3746973" | "4912401" | "4937203" | "5007163" | "5046953" | "5049084" | "5053698").PN. OR ("5363038"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/05/09 16:37
S21 2	4	PCB same connect$ same probe near bumps	US-PGPUB; USPAT	ADJ	ON	2007/05/10 11:23
S21 3	259	probe near bumps	US-PGPUB; USPAT	ADJ	ON	2007/05/10 11:24
S21 4	107	probe near bumps same pads	US-PGPUB; USPAT	ADJ	ON	2007/05/10 11:28
S21 5	113	probe bumps	US-PGPUB; USPAT	ADJ	ON	2007/05/10 11:29
S21 6	51	probe bumps same pads	US-PGPUB; USPAT	ADJ	ON	2007/05/10 11:29
S21 8	1	S216 and plural$ adj wires	US-PGPUB; USPAT	OR	ON	2007/05/10 11:30
S21 9	0	S216 and plural$ adj wires with bump	US-PGPUB; USPAT	OR	ON	2007/05/10 11:31
S22 0	240	plura$ wires same bump	US-PGPUB; USPAT	ADJ	ON	2007/05/10 11:32
S22 1	51	plura$ wires same bump	US-PGPUB; USPAT	ADJ	OFF	2007/05/10 11:32
S22 2	3	plura$ wires near bump	US-PGPUB; USPAT	ADJ	OFF	2007/05/10 11:34
S22 6	2	wires near probe ball	US-PGPUB; USPAT	ADJ	ON	2007/05/10 12:14

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S22 7	505	wafer level burn-in	US-PGPUB; USPAT	ADJ	ON	2007/05/10 12:24
S22 9	207	membrane probe card	US-PGPUB; USPAT	ADJ	ON	2007/05/10 12:26
S23 0	42	membrane probe card with bumps	US-PGPUB; USPAT	ADJ	ON	2007/05/10 12:26
S23 1	4	membrane probe card near bumps	US-PGPUB; USPAT	ADJ	ON	2007/05/10 12:26
S23 2	0	wire group with probe bump	US-PGPUB; USPAT	ADJ	ON	2007/05/10 13:54
S23 4	0	wire same group with probe bump	US-PGPUB; USPAT	ADJ	ON	2007/05/10 13:55
S23 5	188	wire same group with bump	US-PGPUB; USPAT	ADJ	ON	2007/05/10 13:57
S23 6	5	wire same group with bump same probe	US-PGPUB; USPAT	ADJ	ON	2007/05/10 13:58
S23 7	194	wire with bump same probe	US-PGPUB; USPAT	ADJ	ON	2007/05/10 13:58
S23 8	3	two wire with bump same probe	US-PGPUB; USPAT	ADJ	ON	2007/05/10 13:59
S23 9	2	"5267741"	US-PGPUB; USPAT; JPO	OR	ON	2007/05/10 15:10
S24 0	12	"5982183"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:51
S24 1	25	"6286208"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:52
S24 2	1	"6523255"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:52
S24 3	1	"20040032025"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:53
S24 4	48	"5635846"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:53
S24 5	1	"20030032263"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:53
S24 6	4	"6297658"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:55
S24 7	91	"5477160"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:55
S24 8	1	"20040100293"	US-PGPUB; USPAT	OR	ON	2007/05/11 09:56
S24 9	1	"2002022809"	US-PGPUB; USPAT; JPO	OR	ON	2007/05/11 09:56

| S25 0 | 80 | ("3541222" \| "3795037" \| "3862790" \| "3911361" \| "3954317" \| "3963986" \| "4003621" \| "4008300" \| "4038599" \| "4118092" \| "4203203" \| "4221047" \| "4295700" \| "4355199" \| "4400234" \| "4402562" \| "4408814" \| "4509099" \| "4520562" \| "4548451" \| "4555523" \| "4575166" \| "4577918" \| "4622514" \| "4663742" \| "4778950" \| "4793814" \| "4811296" \| "4816754" \| "4820170" \| "4820376" \| "4832609" \| "4875614" \| "4955523" \| "4991290" \| "4998885" \| "5037312" \| "5049084" \| "5099309" \| "5132613" \| "5148103" \| "5258236" \| "5371654").PN. OR ("5635846"). URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/05/11 10:19 |